Heraeus

Electronics

DT1745H

Component Metallization

Description

DT1745H is a lead free Ag paste for front side conductor of chip resistors, with excellent leaching property, acid resistance, adhesion property and electrical characteristics.

Key Features

- Excellent leaching property Excellent acid resistance Excellent adhesive property Excellent electrical characteristics

Typical Properties	
Viscosity	200 – 400 kcps, Brookfield HBDV–III Ultra, SC4-14 spindle & 6R utility cup @ 10 rpm, 25°C
Solids	76.0 ± 2.0%
Solder Leaching	Sn96/Ag3.5/Cu0.5 260 ℃ >60 sec Coverage area >95%

Recommended Processing Guide	
Printing Parameters	200- 400 mesh Polyester or stainless steel screen
Drying Temperature	130 °C for 15 minutes, with exhaust system 150 °C for 10 minutes
Process Temperature (TDS)	Peak temp：840~860 °C Dwell time：8~15 minutes
Recommended Thinner	Heraeus RV-372

DT1745H

Component Metallization

Warranty

Material guaranteed to meet specifications for 6 months from date of manufacturing with proper storage.

Storage

Store in a dry, cool (5 - 25°C), dark place with container tightly shut. Allow paste to come to room temperature prior to opening. Spatulate well before using.

Americas	Asia Pacific	China	Europe, Middle East and Africa
Phone +1 610 825 6050	Phone +65 6571 7649	Phone +86 53 5815 9601	Phone +49 6181 35 4370
electronics.americas@heraeus.com	electronics.apac@heraeus.com	electronics.china@heraeus.com	electronics.emea@heraeus.com

All changes are based on information displayed using the template data_sheet/HET/TFM/print_data_sheet.html.twig.
Version (last updated) 03 Nov 2025